

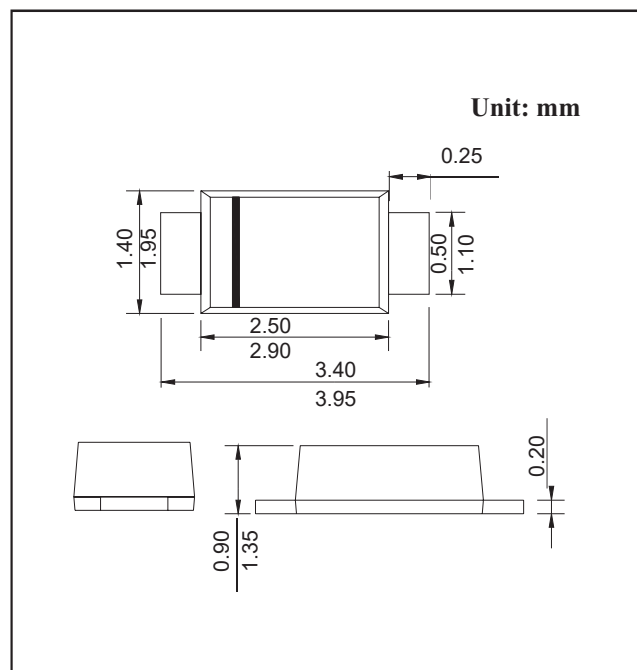
SOD123FL PLASTIC SILICON RECTIFIERS

FEATURES

- For surface mounted application
- Glass passivated device
- Low forward voltage drop
- High current capability
- Easy pick and place
- Plastic material used carriers Underwriters Laboratory Classification 94V-0
- High temperature soldering guaranteed: 250 C/10 seconds

MECHANICAL DATA

- Case : JEDEC SOD-123FL molded plastic bodyover
- passivated chip
- Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end Mounting Position: Any



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter		Symbols	A1	A2	A3	A4	A5	A6	A7	Unis
Maximum Recurrent Peak Reverse Voltage		VRRM	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage		VRMS	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage		VDC	50	100	200	400	600	800	1000	Volts
Maximum average Forward Rectified Current 0.375"(9.5mm) lead length at TA=75°C		l(AV)	1.0							Amp
Peak Forward Surge Current (8.3ms half sine-wave superimposed on rated load (JEDEC method) TA=75°C		IFSM	30.0							Amps
Maximum Instantaneous Forward Voltage at 1.0 A		VF	1.0							Volts
Maximum Reverse current at rated DC Blocking Voltage	TA =25 °C	IR	5.0							μA
	TA =100 °C		50. 0							
Typical Thermal resistance (Note 2)		RθJA	65.0							°C/W
Typical Junction Capacitance(Note 1)		CJ	10.0							pF
Maximum DC Blocking Voltage		TA	+150							°C
temperature Operating and Storage temperature Range		TJ TSTG	-55 to+150							°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V DC.

2. Thermal resistance from junction to ambient and from junction to lead at 0.375"(9.5mm) lead length, P.C.B. mounted

RATINGS AND CHARACTERISTIC CURVES

FIG. 1- FORWARD CURRENT DERATING CURVE

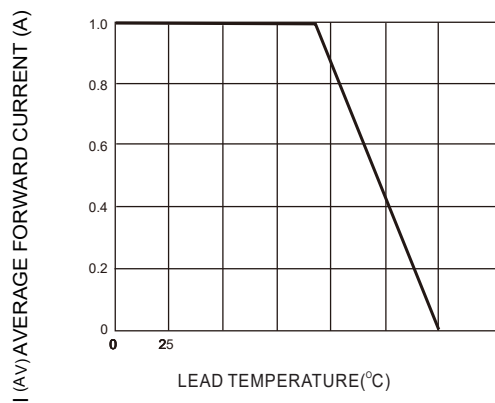


FIG. 2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

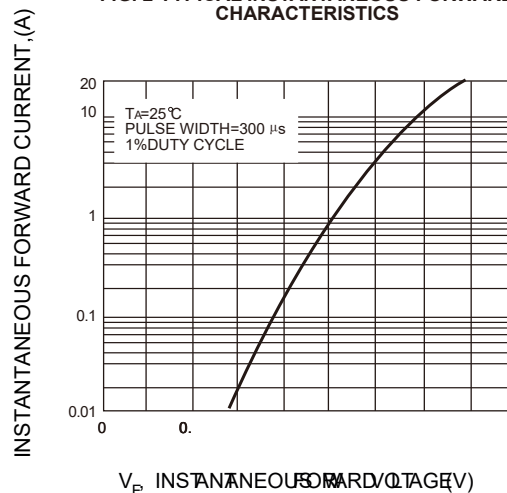


FIG. 3-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

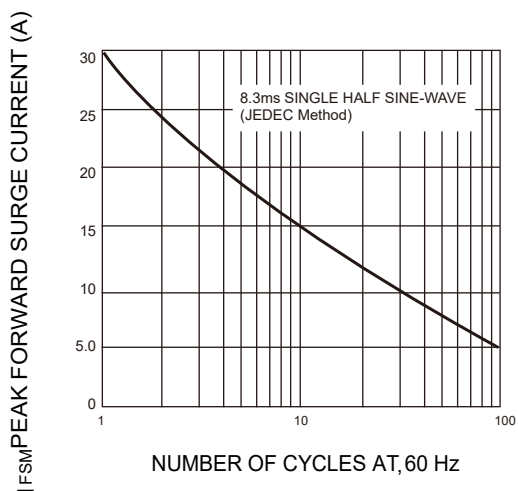


FIG. 4-TYPICAL JUNCTION CAPACITANCE

